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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, QEI, POR, PWM, WDT
Number of I/O	68
Program Memory Size	66KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-TQFP
Supplier Device Package	80-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f5016-20e-pt

TABLE 1-1: I/O PIN DESCRIPTIONS FOR dsPIC30F5015 (CONTINUED)

Pin Name	Pin Type	Buffer Type	Description
$\overline{MCLR}$	I/P	ST	Master Clear (Reset) input or programming voltage input. This pin is an active-low Reset to the device.
OCFA OC1-OC4	I O	ST —	Compare Fault A input (for Compare channels 1, 2, 3 and 4). Compare outputs 1 through 4.
OSC1 OSC2	I I/O	ST/CMOS —	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
PGD PGC	I/O I	ST ST	In-Circuit Serial Programming™ data input/output pin. In-Circuit Serial Programming clock input pin.
RB0-RB15	I/O	ST	PORTB is a bidirectional I/O port.
RC13-RC15	I/O	ST	PORTC is a bidirectional I/O port.
RD0-RD11	I/O	ST	PORTD is a bidirectional I/O port.
RE0-RE7	I/O	ST	PORTE is a bidirectional I/O port.
RF0-RF6	I/O	ST	PORTF is a bidirectional I/O port.
RG2-RG3 RG6-RG9	I/O I/O	ST ST	PORTG is a bidirectional I/O port.
SCK1 SDI1 SDO1 $\overline{SS1}$ SCK2 SDI2 SDO2 $\overline{SS2}$	I/O I O I I/O I O I	ST ST — ST ST ST — ST	Synchronous serial clock input/output for SPI1. SPI1 Data In. SPI1 Data Out. SPI1 Slave Synchronization. Synchronous serial clock input/output for SPI2. SPI2 Data In. SPI2 Data Out. SPI2 Slave Synchronization.
SCL SDA	I/O I/O	ST ST	Synchronous serial clock input/output for I^2C™. Synchronous serial data input/output for I^2C.
SOSCO SOSCI	O I	— ST/CMOS	32 kHz low-power oscillator crystal output. 32 kHz low-power oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
T1CK T4CK	I I	ST ST	Timer1 external clock input. Timer4 external clock input.
U1RX U1TX	I O	ST —	UART1 Receive. UART1 Transmit.
V_{DD}	P	—	Positive supply for logic and I/O pins.
V_{SS}	P	—	Ground reference for logic and I/O pins.
V_{REF+}	I	Analog	Analog Voltage Reference (High) input.
V_{REF-}	I	Analog	Analog Voltage Reference (Low) input.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input
ST = Schmitt Trigger input with CMOS levels; O = Output
I = Input; P = Power

3.1.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

This architecture fetches 24-bit wide program memory. Consequently, instructions are always aligned. However, as the architecture is modified Harvard, data can also be present in program space.

There are two methods by which program space can be accessed; via special table instructions, or through the remapping of a 16K word program space page into the upper half of data space (see **Section 3.1.2 "Data Access from Program Memory Using Program Space Visibility"**). The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the least significant word of any address within program space, without going through data space. The TBLRDH and TBLWTH instructions are the only method whereby the upper 8 bits of a program space word can be accessed as data.

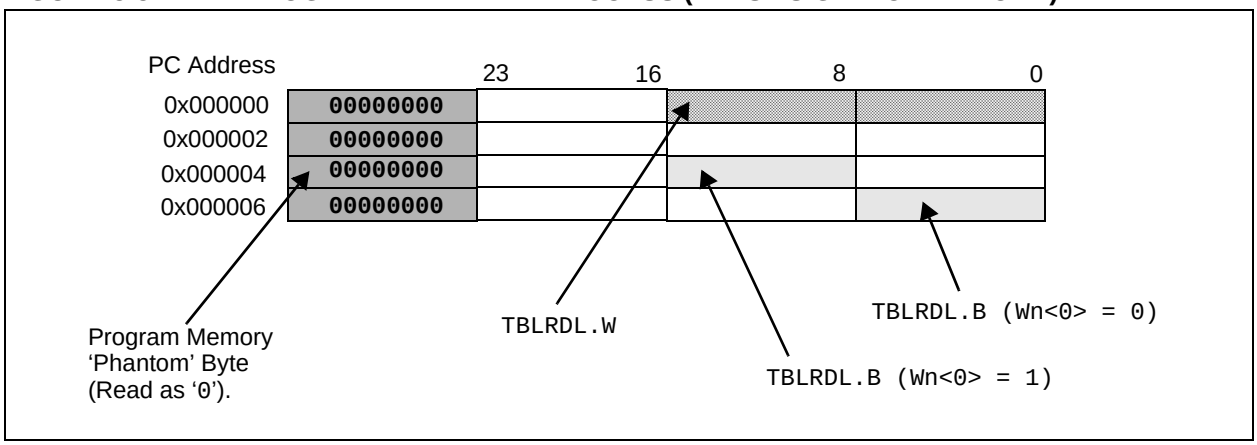
The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit word wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant word, and TBLRDH and TBLWTH access the space that contains the MSB.

Figure 3-2 shows how the EA is created for table operations and data space accesses (PSV = 1). Here, P<23:0> refers to a program space word, whereas D<15:0> refers to a data space word.

A set of table instructions are provided to move byte or word-sized data to and from program space.

1. **TBLRDL:** Table Read Low
   Word: Read the least significant word of the program address;
   P<15:0> maps to D<15:0>.
   Byte: Read one of the LSBs of the program address;
   P<7:0> maps to the destination byte when byte select = 0;
   P<15:8> maps to the destination byte when byte select = 1.
2. **TBLWTL:** Table Write Low (refer to **Section 6.0 "Flash Program Memory"** for details on Flash Programming).
3. **TBLRDH:** Table Read High
   Word: Read the most significant word of the program address;
   P<23:16> maps to D<7:0>; D<15:8> always is = 0.
   Byte: Read one of the MSBs of the program address;
   P<23:16> maps to the destination byte when byte select = 0;
   The destination byte will always be = 0 when byte select = 1.
4. **TBLWTH:** Table Write High (refer to **Section 6.0 "Flash Program Memory"** for details on Flash Programming).

FIGURE 3-3: PROGRAM DATA TABLE ACCESS (LEAST SIGNIFICANT WORD)



4.1.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP Accumulator class of instructions provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, Move and Accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

Note: For the MOV instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared between both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by Move and Accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-bit Literal
- 16-bit Literal

Note: Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.1.4 MAC INSTRUCTIONS

The dual source operand DSP instructions (CLR, ED, EDAC, MAC, MPY, MPY.N, MOVSAC and MSC), also referred to as MAC instructions, utilize a simplified set of addressing modes to allow the user to effectively manipulate the data pointers through Register Indirect tables.

The two source operand prefetch registers must be a member of the set {W8, W9, W10, W11}. For data reads, W8 and W9 will always be directed to the X RAGU and W10 and W11 will always be directed to the Y AGU. The effective addresses generated (before and after modification) must, therefore, be valid addresses within X data space for W8 and W9 and Y data space for W10 and W11.

Note: Register Indirect with Register Offset Addressing is only available for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the MAC class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.1.5 OTHER INSTRUCTIONS

Besides the various addressing modes outlined above, some instructions use literal constants of various sizes. For example, BRA (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the DISI instruction uses a 14-bit unsigned literal field. In some instructions, such as ADD Acc, the source of an operand or result is implied by the opcode itself. Certain operations, such as NOP, do not have any operands.

4.2 Modulo Addressing

Modulo Addressing is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either data or program space (since the data pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into program space) and Y data spaces. Modulo Addressing can operate on any W register pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing, since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can only be configured to operate in one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers) based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers which have a power-of-2 length. As these buffers satisfy the start and end address criteria, they may operate in a Bidirectional mode, (i.e., address boundary checks will be performed on both the lower and upper address boundaries).

4.2.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and an ending address be specified and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 3-3).

Note:	Y-space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

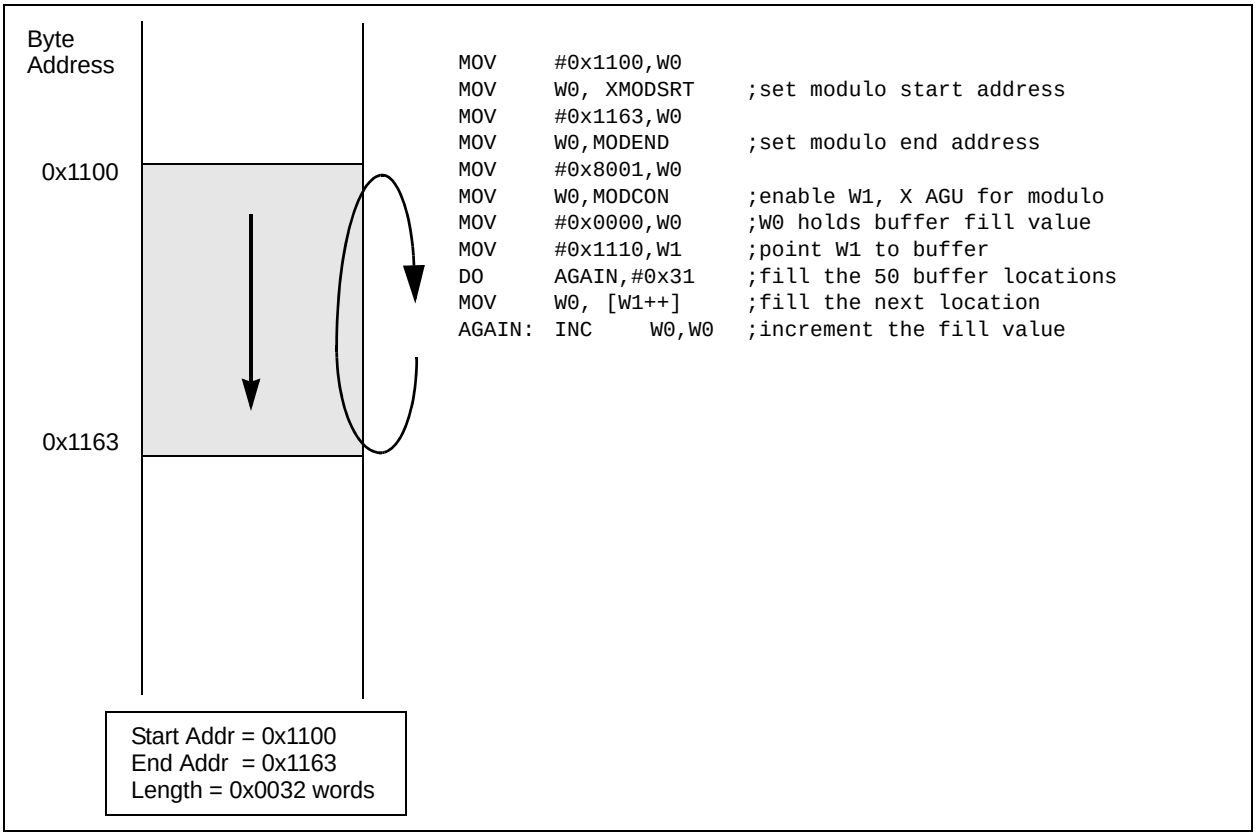
4.2.2 W ADDRESS REGISTER SELECTION

The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags, as well as a W register field to specify the W Address registers. The XWM and YWM fields select which registers will operate with Modulo Addressing. If XWM = 15, X RAGU and X WAGU Modulo Addressing are disabled. Similarly, if YWM = 15, Y AGU Modulo Addressing is disabled.

The X Address Space Pointer W register (XWM) to which Modulo Addressing is to be applied, is stored in MODCON<3:0> (see Table 3-3). Modulo Addressing is enabled for X data space when XWM is set to any value other than 15 and the XMODEN bit is set at MODCON<15>.

The Y Address Space Pointer W register (YWM) to which Modulo Addressing is to be applied, is stored in MODCON<7:4>. Modulo Addressing is enabled for Y data space when YWM is set to any value other than 15 and the YMODEN bit is set at MODCON<14>.

FIGURE 4-1: MODULO ADDRESSING OPERATION EXAMPLE




```
MOV     #0x1100,W0
MOV     W0, XMODSRT     ;set modulo start address
MOV     #0x1163,W0
MOV     W0,MODEND       ;set modulo end address
MOV     #0x8001,W0
MOV     W0,MODCON       ;enable W1, X AGU for modulo
MOV     #0x0000,W0      ;W0 holds buffer fill value
MOV     #0x1110,W1      ;point W1 to buffer
DO      AGAIN,#0x31     ;fill the 50 buffer locations
MOV     W0, [W1++]      ;fill the next location
AGAIN:  INC     W0,W0   ;increment the fill value
```

TABLE 5-2: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC30F5015(1)

SFR Name	ADR	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
INTCON1	0080	NSTDIS	—	—	—	—	OVATE	OVBTE	COVTE	—	—	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000 0000 0000 0000
INTCON2	0082	ALTIVT	DISI	—	—	—	—	—	—	—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000 0000 0000 0000
IFS0	0084	CNIF	MI2CIF	SI2CIF	NVMIF	ADIF	U1TXIF	U1RXIF	SPI1IF	T3IF	T2IF	OC2IF	IC2IF	T1IF	OC1IF	IC1IF	INT0IF	0000 0000 0000 0000
IFS1	0086	—	—	IC4IF	IC3IF	C1IF	SPI2IF	—	—	INT2IF	T5IF	T4IF	OC4IF	OC3IF	—	—	INT1IF	0000 0000 0000 0000
IFS2	0088	—	—	—	FLTBIF	FLTAIF	—	—	QEIIF	PWMIF	—	INT4IF	INT3IF	—	—	—	—	0000 0000 0000 0000
IEC0	008C	CNIE	MI2CIE	SI2CIE	NVMIE	ADIE	U1TXIE	U1RXIE	SPI1IE	T3IE	T2IE	OC2IE	IC2IE	T1IE	OC1IE	IC1IE	INT0IE	0000 0000 0000 0000
IEC1	008E	—	—	IC4IE	IC3IE	C1IE	SPI2IE	—	—	INT2IE	T5IE	T4IE	OC4IE	OC3IE	—	—	INT1IE	0000 0000 0000 0000
IEC2	0090	—	—	—	FLTBIE	FLTAIE	—	—	QEIIE	PWMIE	—	INT4IE	INT3IE	—	—	—	—	0000 0000 0000 0000
IPC0	0094	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			0100 0100 0100 0100
IPC1	0096	—	T31P<2:0>			—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			0100 0100 0100 0100
IPC2	0098	—	ADIP<2:0>			—	U1TXIP<2:0>			—	U1RXIP<2:0>			—	SPI1IP<2:0>			0100 0100 0100 0100
IPC3	009A	—	CNIP<2:0>			—	MI2CIP<2:0>			—	SI2CIP<2:0>			—	NVMIP<2:0>			0100 0100 0100 0100
IPC4	009C	—	OC3IP<2:0>			—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0100 0000 0000 0100
IPC5	009E	—	INT2IP<2:0>			—	T5IP<2:0>			—	T4IP<2:0>			—	OC4IP<2:0>			0100 0100 0100 0100
IPC6	00A0	—	C1IP<2:0>			—	SPI2IP<2:0>			—	—	—	—	—	—	—	—	0100 0100 0000 0000
IPC7	00A2	—	—	—	—	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			0000 0000 0100 0100
IPC8	00A4	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000 0000 0000 0000
IPC9	00A6	—	PWMIP<2:0>			—	—	—	—	—	INT41IP<2:0>			—	INT3IP<2:0>				0100 0000 0100 0100
IPC10	00A8	—	FLTAIP<2:0>			—	—	—	—	—	—	—	—	—	QEIIP<2:0>			0100 0000 0000 0100
IPC11	00AA	—	—	—	—	—	—	—	—	—	—	—	—	—	FLTBIP<2:0>			0000 0000 0000 0100

Legend: — = unimplemented bit, read as '0'

Note 1: Refer to *the "dsPIC30F Family Reference Manual"* (DS70046) for descriptions of register bit fields.

9.0 TIMER1 MODULE

Note:	This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "*dsPIC30F Family Reference Manual*" (DS70046). For more information on the device instruction set and programming, refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157).

This section describes the 16-bit General Purpose (GP) Timer1 module and associated operational modes.

Note:	Timer1 is a Type A timer. Please refer to the specifications for a Type A timer in **Section 24.0 Electrical Characteristics** of this document.

The following sections provide a detailed description, including setup and control registers along with associated block diagrams for the operational modes of the timers.

The Timer1 module is a 16-bit timer which can serve as the time counter for the real-time clock, or operate as a free-running interval timer/counter. The 16-bit timer has the following modes:

- 16-bit Timer
- 16-bit Synchronous Counter
- 16-bit Asynchronous Counter

Further, the following operational characteristics are supported:

- Timer gate operation
- Selectable prescaler settings
- Timer operation during CPU Idle and Sleep modes
- Interrupt on 16-bit Period register match or falling edge of external gate signal

These operating modes are determined by setting the appropriate bit(s) in the 16-bit SFR, T1CON. Figure 9-1 presents a block diagram of the 16-bit timer module.

16-bit Timer Mode: In the 16-bit Timer mode, the timer increments on every instruction cycle up to a match value, preloaded into the Period register, PR1, then resets to '0' and continues to count.

When the CPU goes into the Idle mode, the timer will stop incrementing, unless the TSIDL (T1CON<13>) bit = 0. If TSIDL = 1, the timer module logic will resume the incrementing sequence upon termination of the CPU Idle mode.

16-bit Synchronous Counter Mode: In the 16-bit Synchronous Counter mode, the timer increments on the rising edge of the applied external clock signal, which is synchronized with the internal phase clocks. The timer counts up to a match value preloaded in PR1, then resets to '0' and continues.

When the CPU goes into the Idle mode, the timer will stop incrementing, unless the respective TSIDL bit = 0. If TSIDL = 1, the timer module logic will resume the incrementing sequence upon termination of the CPU Idle mode.

16-bit Asynchronous Counter Mode: In the 16-bit Asynchronous Counter mode, the timer increments on every rising edge of the applied external clock signal. The timer counts up to a match value preloaded in PR1, then resets to '0' and continues.

When the timer is configured for the Asynchronous mode of operation and the CPU goes into the Idle mode, the timer will stop incrementing if TSIDL = 1.

NOTES:

14.4 Programmable Digital Noise Filters

The digital noise filter section is responsible for rejecting noise on the incoming quadrature signals. Schmitt Trigger inputs and a three-clock cycle delay filter combine to reject low-level noise and large, short duration noise spikes that typically occur in noise prone applications, such as a motor system.

The filter ensures that the filtered output signal is not permitted to change until a stable value has been registered for three consecutive clock cycles.

For the QEA, QEB and INDX pins, the clock divide frequency for the digital filter is programmed by bits QECK<2:0> (DFLTCON<6:4>) and are derived from the base instruction cycle TCY.

To enable the filter output for channels QEA, QEB and INDX, the QEOUT bit must be '1'. The filter network for all channels is disabled on POR and BOR.

14.5 Alternate 16-bit Timer/Counter

When the QEI module is not configured for the QEI mode, QEIM<2:0> = 001, the module can be configured as a simple 16-bit timer/counter. The setup and control of the auxiliary timer is accomplished through the QEICON SFR register. This timer functions identically to Timer1. The QEA pin is used as the timer clock input.

When configured as a timer, the POSCNT register serves as the Timer Count register and the MAXCNT register serves as the Period register. When a Timer/Period register match occurs, the QEI interrupt flag will be asserted.

The only exception between the general purpose timers and this timer is the added feature of external up/down input select. When the UPDN pin is asserted high, the timer will increment up. When the UPDN pin is asserted low, the timer will be decremented.

Note:	Changing the operational mode (i.e., from QEI to Timer or vice versa), will not affect the Timer/Position Count register contents.

The UPDN control/Status bit (QEICON<11>) can be used to select the count direction state of the Timer register. When UPDN = 1, the timer will count up. When UPDN = 0, the timer will count down.

In addition, control bit, UDSRC (QEICON<0>), determines whether the timer count direction state is based on the logic state written into the UPDN control/Status bit (QEICON<11>), or the QEB pin state. When UDSRC = 1, the timer count direction is controlled from the QEB pin. Likewise, when UDSRC = 0, the timer count direction is controlled by the UPDN bit.

Note:	This timer does not support the External Asynchronous Counter mode of operation. If using an external clock source, the clock will automatically be synchronized to the internal instruction cycle.

14.6 QEI Module Operation During CPU Sleep Mode

14.6.1 QEI OPERATION DURING CPU SLEEP MODE

The QEI module will be halted during the CPU Sleep mode.

14.6.2 TIMER OPERATION DURING CPU SLEEP MODE

During CPU Sleep mode, the timer will not operate, because the internal clocks are disabled.

14.7 QEI Module Operation During CPU Idle Mode

Since the QEI module can function as a Quadrature Encoder Interface, or as a 16-bit timer, the following section describes operation of the module in both modes.

14.7.1 QEI OPERATION DURING CPU IDLE MODE

When the CPU is placed in the Idle mode, the QEI module will operate if the QEISIDL bit (QEICON<13>) = 0. This bit defaults to a logic '0' upon executing POR and BOR. For halting the QEI module during the CPU Idle mode, QEISIDL should be set to '1'.

14.7.2 TIMER OPERATION DURING CPU IDLE MODE

When the CPU is placed in the Idle mode and the QEI module is configured in the 16-bit Timer mode, the 16-bit timer will operate if the QEISIDL bit (QEICON<13>) = 0. This bit defaults to a logic '0' upon executing POR and BOR. For halting the timer module during the CPU Idle mode, QEISIDL should be set to '1'.

If the QEISIDL bit is cleared, the timer will function normally, as if the CPU Idle mode had not been entered.

15.7.2 DEAD-TIME ASSIGNMENT

The DTCON2 SFR contains control bits that allow the dead times to be assigned to each of the complementary outputs. Table 15-1 summarizes the function of each dead-time selection control bit.

TABLE 15-1: DEAD-TIME SELECTION BITS

Bit	Selects
DTS1A	PWM1L/PWM1H active edge dead time.
DTS1I	PWM1L/PWM1H inactive edge dead time.
DTS2A	PWM2L/PWM2H active edge dead time.
DTS2I	PWM2L/PWM2H inactive edge dead time.
DTS3A	PWM3L/PWM3H active edge dead time.
DTS3I	PWM3L/PWM3H inactive edge dead time.
DTS4A	PWM4L/PWM4H active edge dead time.
DTS4I	PWM4L/PWM4H inactive edge dead time.

15.7.3 DEAD-TIME RANGES

The amount of dead time provided by each dead-time unit is selected by specifying the input clock prescaler value and a 6-bit unsigned value. The amount of dead time provided by each unit may be set independently.

Four input clock prescaler selections have been provided to allow a suitable range of dead times, based on the device operating frequency. The clock prescaler option may be selected independently for each of the two dead-time values. The dead-time clock prescaler values are selected using the DTAPS<1:0> and DTBPS<1:0> control bits in the DTCON1 SFR. One of four clock prescaler options (T_{CY}, 2 T_{CY}, 4 T_{CY} or 8 T_{CY}) may be selected for each of the dead-time values.

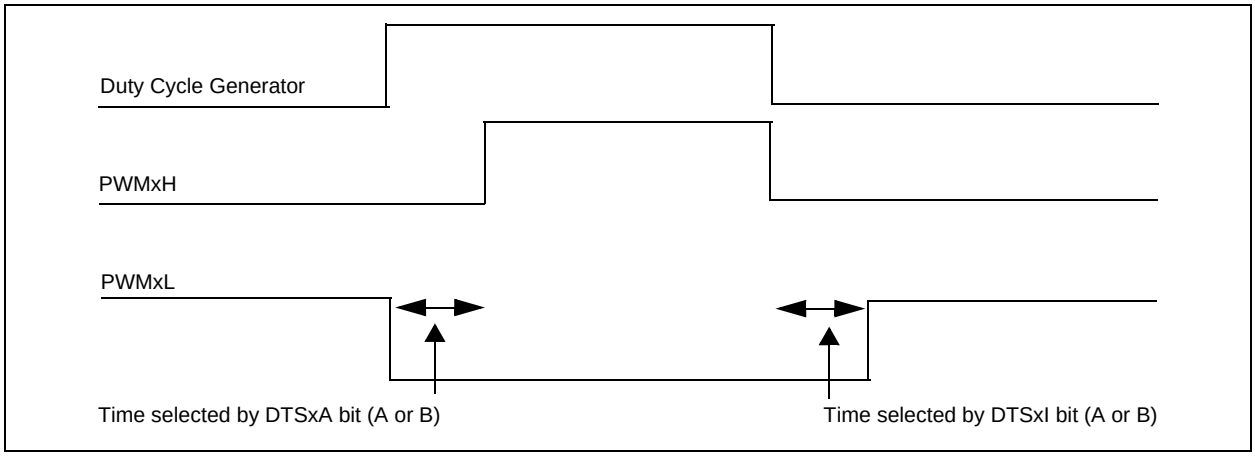
After the prescaler values are selected, the dead time for each unit is adjusted by loading two 6-bit unsigned values into the DTCON1 SFR.

The dead-time unit prescalers are cleared on the following events:

- On a load of the down timer due to a duty cycle comparison edge event.
- On a write to the DTCON1 or DTCON2 registers.
- On any device Reset.

Note:	The user should not modify the DTCON1 or DTCON2 values while the PWM module is operating (PTEN = 1). Unexpected results may occur.

FIGURE 15-4: DEAD-TIME TIMING DIAGRAM



NOTES:

TABLE 16-1: SPI1 REGISTER MAP(1)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
SPI1STAT	0220	SPIEN	—	SPISIDL	—	—	—	—	—	—	SPIROV	—	—	—	—	SPITBF	SPIRBF	0000 0000 0000 0000
SPI1CON	0222	—	FRMEN	SPIFSD	—	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE2	SPRE1	SPRE0	PPRE1	PPRE0	0000 0000 0000 0000
SPI1BUF	0224	Transmit and Receive Buffer																0000 0000 0000 0000

Legend: — = unimplemented bit, read as '0'

Note 1: Refer to the *"dsPIC30F Family Reference Manual"* (DS70046) for descriptions of register bit fields.

TABLE 16-2: SPI2 REGISTER MAP(1)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
SPI2STAT	0226	SPIEN	—	SPISIDL	—	—	—	—	—	—	SPIROV	—	—	—	—	SPITBF	SPIRBF	0000 0000 0000 0000
SPI2CON	0228	—	FRMEN	SPIFSD	—	DISSDO	MODE16	SMP	CKE	SSEN	CKP	MSTEN	SPRE2	SPRE1	SPRE0	PPRE1	PPRE0	0000 0000 0000 0000
SPI2BUF	022A	Transmit and Receive Buffer																0000 0000 0000 0000

Legend: — = unimplemented bit, read as '0'

Note 1: Refer to the *"dsPIC30F Family Reference Manual"* (DS70046) for descriptions of register bit fields.

FIGURE 18-2: UART RECEIVER BLOCK DIAGRAM

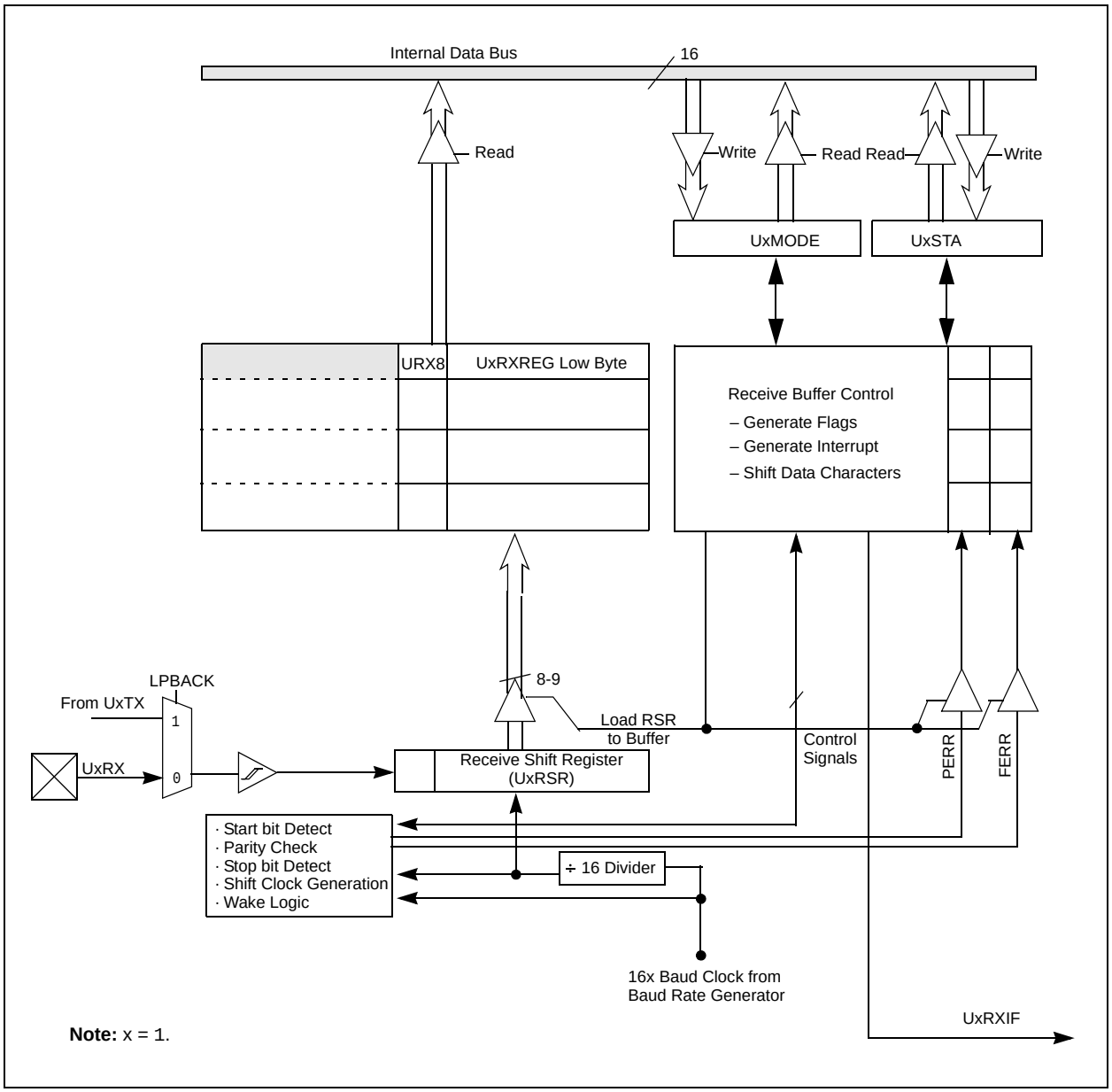
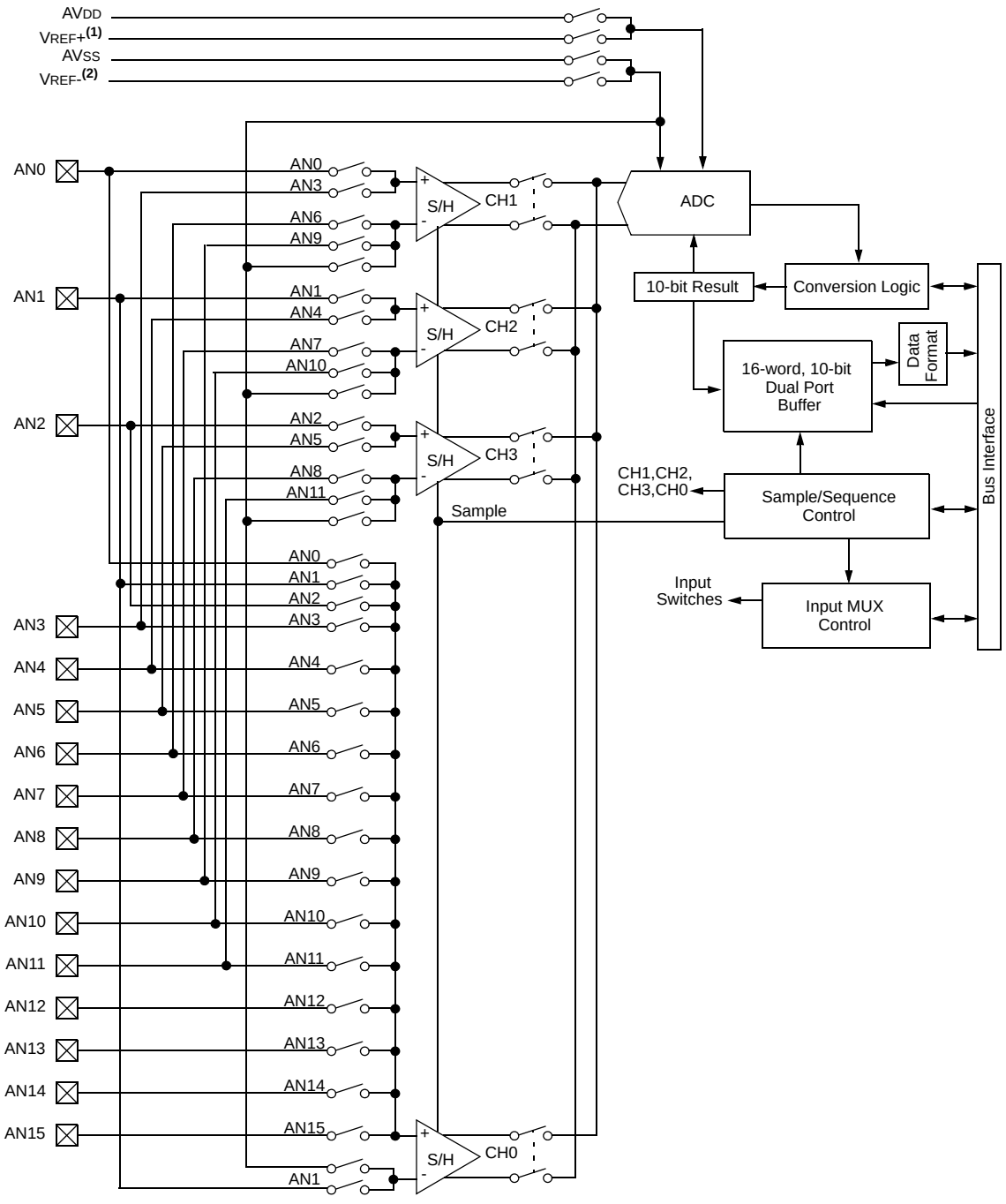


FIGURE 20-1: 10-BIT HIGH-SPEED A/D FUNCTIONAL BLOCK DIAGRAM



Note 1: VREF+ is multiplexed with AN0 in the dsPIC30F5015 variant.

2: VREF- is multiplexed with AN1 in the dsPIC30F5015 variant.

FIGURE 21-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD})

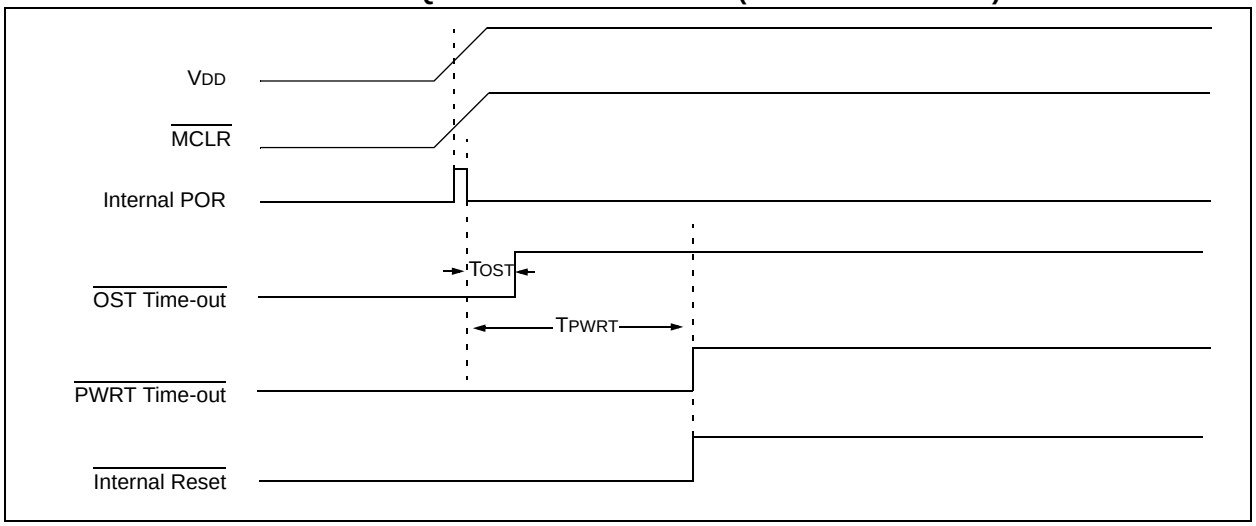


FIGURE 21-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

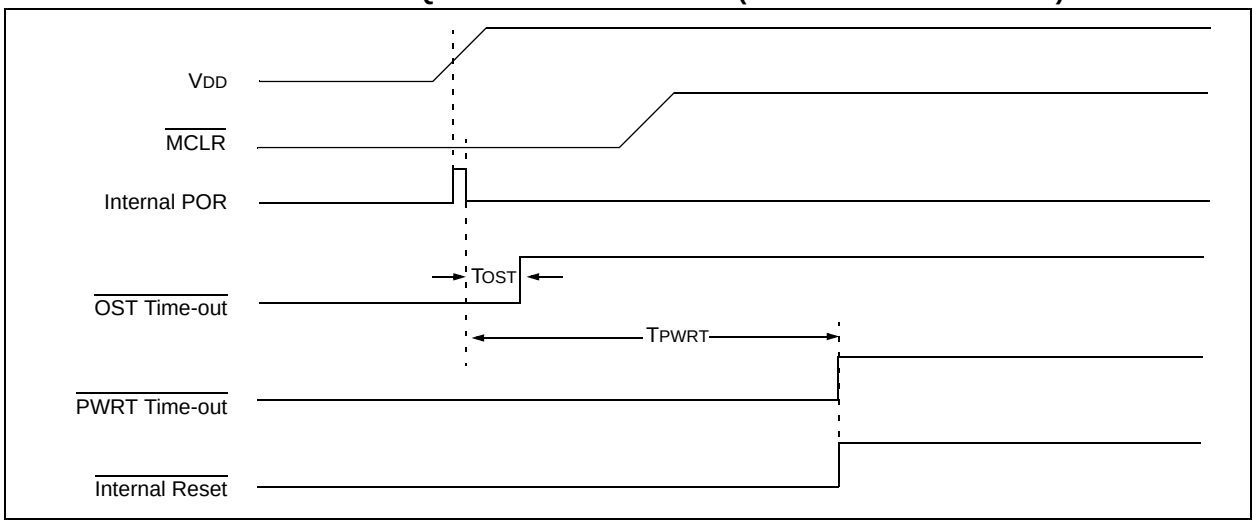


FIGURE 21-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

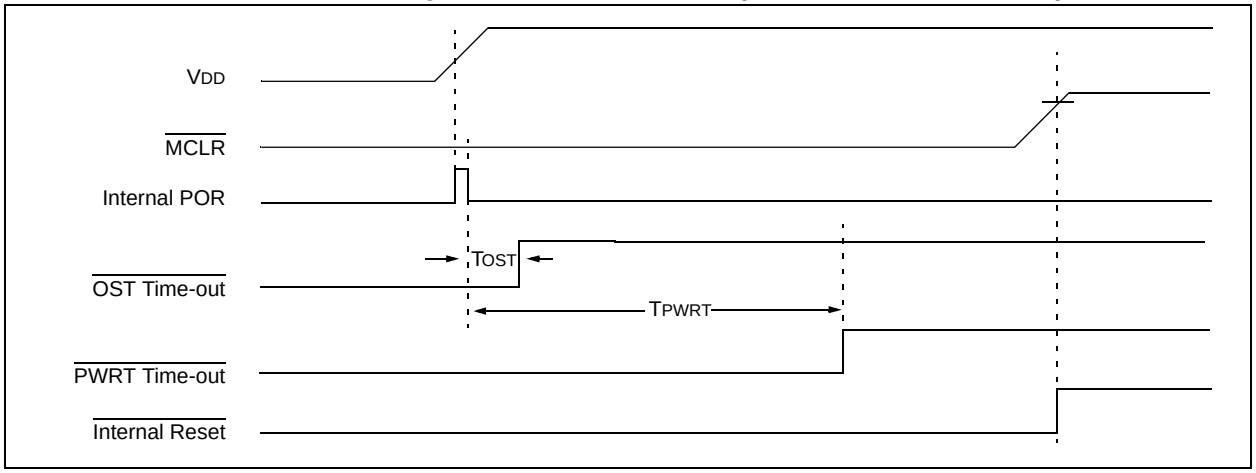


Table 21-5 shows the Reset conditions for the RCON register. Since the control bits within the RCON register are R/W, the information in the table implies that all the bits are negated prior to the action specified in the condition column.

TABLE 21-5: INITIALIZATION CONDITION FOR RCON REGISTER CASE 1

Condition	Program Counter	TRAPR	IOPUWR	EXTR	SWR	WDTO	IDLE	SLEEP	POR	BOR
Power-on Reset	0x000000	0	0	0	0	0	0	0	1	1
Brown-out Reset	0x000000	0	0	0	0	0	0	0	0	1
$\overline{\text{MCLR}}$ Reset during normal operation	0x000000	0	0	1	0	0	0	0	0	0
Software Reset during normal operation	0x000000	0	0	0	1	0	0	0	0	0
$\overline{\text{MCLR}}$ Reset during Sleep	0x000000	0	0	1	0	0	0	1	0	0
$\overline{\text{MCLR}}$ Reset during Idle	0x000000	0	0	1	0	0	1	0	0	0
WDT Time-out Reset	0x000000	0	0	0	0	1	0	0	0	0
WDT Wake-up	PC + 2	0	0	0	0	1	0	1	0	0
Interrupt Wake-up from Sleep	PC + 2(1)	0	0	0	0	0	0	1	0	0
Clock Failure Trap	0x000004	0	0	0	0	0	0	0	0	0
Trap Reset	0x000000	1	0	0	0	0	0	0	0	0
Illegal Operation Trap	0x000000	0	1	0	0	0	0	0	0	0

Note 1: When the wake-up is due to an enabled interrupt, the PC is loaded with the corresponding interrupt vector.

Table 21-6 shows a second example of the bit conditions for the RCON register. In this case, it is not assumed the user has set/cleared specific bits prior to action specified in the condition column.

TABLE 21-6: INITIALIZATION CONDITION FOR RCON REGISTER CASE 2

Condition	Program Counter	TRAPR	IOPUWR	EXTR	SWR	WDTO	IDLE	SLEEP	POR	BOR
Power-on Reset	0x000000	0	0	0	0	0	0	0	1	1
Brown-out Reset	0x000000	u	u	u	u	u	u	u	0	1
$\overline{\text{MCLR}}$ Reset during normal operation	0x000000	u	u	1	0	0	0	0	u	u
Software Reset during normal operation	0x000000	u	u	0	1	0	0	0	u	u
$\overline{\text{MCLR}}$ Reset during Sleep	0x000000	u	u	1	u	0	0	1	u	u
$\overline{\text{MCLR}}$ Reset during Idle	0x000000	u	u	1	u	0	1	0	u	u
WDT Time-out Reset	0x000000	u	u	0	0	1	0	0	u	u
WDT Wake-up	PC + 2	u	u	u	u	1	u	1	u	u
Interrupt Wake-up from Sleep	PC + 2(1)	u	u	u	u	u	u	1	u	u
Clock Failure Trap	0x000004	u	u	u	u	u	u	u	u	u
Trap Reset	0x000000	1	u	u	u	u	u	u	u	u
Illegal Operation Reset	0x000000	u	1	u	u	u	u	u	u	u

Legend: u = unchanged

Note 1: When the wake-up is due to an enabled interrupt, the PC is loaded with the corresponding interrupt vector.

23.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit™ 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows® programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit™ 2 enables in-circuit debugging on most PIC® microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

23.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

23.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

24.1 DC Characteristics

TABLE 24-1: OPERATING MIPS VS. VOLTAGE FOR dsPIC30F5015

VDD Range (in Volts)	Temp Range (in °C)	Max MIPS	
		dsPIC30F5015-30I	dsPIC30F5015-20E
4.5-5.5	-40 to +85	30	—
4.5-5.5	-40 to +125	—	20
3.0-3.6	-40 to +85	20	—
3.0-3.6	-40 to +125	—	15
2.5-3.0	-40 to +85	10	—

TABLE 24-2: OPERATING MIPS VS. VOLTAGE FOR dsPIC30F5016

VDD Range (in Volts)	Temp Range (in °C)	Max MIPS	
		dsPIC30F5016-30I	dsPIC30F5016-20E
4.5-5.5	-40 to +85	30	—
4.5-5.5	-40 to +125	—	20
3.0-3.6	-40 to +85	20	—
3.0-3.6	-40 to +125	—	15
2.5-3.0	-40 to +85	10	—

TABLE 24-3: THERMAL OPERATING CONDITIONS FOR dsPIC30F5015/5016

Rating	Symbol	Min	Typ	Max	Unit
dsPIC30F5015-30I/dsPIC30F5016-30I					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
dsPIC30F5015-20E/dsPIC30F5016-20E					
Operating Junction Temperature Range	TJ	-40	—	+150	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: $P_{INT} = V_{DD} \times \left(I_{DD} - \sum I_{OH}\right)$ I/O Pin Power Dissipation: $P_{I/O} = \sum(\{V_{DD} - V_{OH}\} \times I_{OH}) + \sum(V_{OL} \times I_{OL})$	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 24-4: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 80-pin TQFP (12x12x1mm)	θJA	39	—	°C/W	**1**
Package Thermal Resistance, 64-pin TQFP (10x10x1mm)	θJA	39	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-ja (θJA) numbers are achieved by package simulations.

TABLE 24-15: PLL CLOCK TIMING SPECIFICATIONS (V_{DD} = 2.5 TO 5.5 V)

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Input Frequency Range(2)	4	—	10	MHz	EC with 4x PLL
			4	—	10	MHz	EC with 8x PLL
			4	—	7.5(4)	MHz	EC with 16x PLL
			4	—	10	MHz	XT with 4x PLL
			4	—	10	MHz	XT with 8x PLL
			4	—	7.5(4)	MHz	XT with 16x PLL
			5(3)	—	10	MHz	HS/2 with 4x PLL
			5(3)	—	10	MHz	HS/2 with 8x PLL
			5(3)	—	7.5(4)	MHz	HS/2 with 16x PLL
			4	—	8.33(3)	MHz	HS/3 with 4x PLL
			4	—	8.33(3)	MHz	HS/3 with 8x PLL
			4	—	7.5(4)	MHz	HS/3 with 16x PLL
OS51	FSYS	On-Chip PLL Output(2)	16	—	120	MHz	EC, XT, HS/2, HS/3 modes with PLL
OS52	TLOC	PLL Start-up Time (Lock Time)	—	20	50	µs	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Limited by oscillator frequency range.

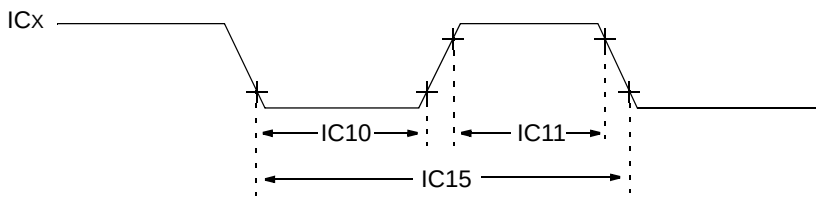
4: Limited by device operating frequency range.

TABLE 24-16: PLL JITTER

AC CHARACTERISTICS		Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**	
OS61	x4 PLL	—	0.251	0.413	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V
		—	0.251	0.413	%	-40°C ≤TA ≤+125°C	VDD = 3.0 to 3.6V
		—	0.256	0.47	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V
		—	0.256	0.47	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V
	x8 PLL	—	0.355	0.584	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V
		—	0.355	0.584	%	-40°C ≤TA ≤+125°C	VDD = 3.0 to 3.6V
		—	0.362	0.664	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V
		—	0.362	0.664	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V
	x16 PLL	—	0.67	0.92	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V
		—	0.632	0.956	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V
		—	0.632	0.956	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-9: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



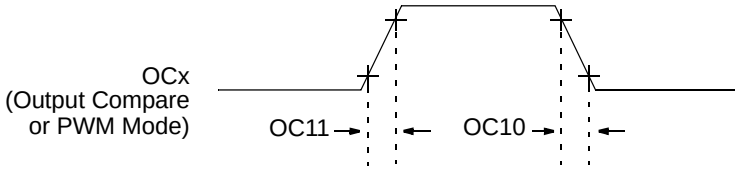
Note: Refer to Figure 24-2 for load conditions.

TABLE 24-27: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**		**Min**	**Max**	**Units**	**Conditions**
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 TCY + 20	—	ns	—
			With Prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No Prescaler	0.5 TCY + 20	—	ns	—
			With Prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(2 TCY + 40)/N	—	ns	N = prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-10: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 24-2 for load conditions.

TABLE 24-28: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

APPENDIX A: REVISION HISTORY

Revision A (July 2005)

Original data sheet for dsPIC30F5015/5016 devices.

Revision B (September 2006)

Revision B of this data sheet reflects these changes:

- Base instruction CP1 removed (see Table 22-2)
- Supported I^2C Slave Addresses (see Table 17-1)
- ADC Conversion Clock selection (see **Section 20.0 "10-bit High-Speed Analog-to-Digital Converter (ADC) Module"**)
- Revised Electrical Characteristics
  - Operating current (I_{DD}) specifications (see Table 24-6)
  - Idle current (I_{IDLE}) specifications (see Table 24-7)
  - Power-down current (I_{PD}) specifications (see Table 24-8)
  - I/O Pin input specifications (see Table 24-9)
  - BOR voltage limits (see Table 24-11)
  - Watchdog Timer limits (see Table 24-21)

Revision C (January 2007)

This revision includes updates to the packaging diagram.

Revision D (March 2008)

This revision reflects these updates:

- Changed the location of the input reference in the 10-bit High-Speed ADC Functional Block Diagram (see Figure 20-1)
- Added FUSE Configuration Register (FICD) details (see **Section 21.6 "Device Configuration Registers"** and Table 21-8)
- Added Note 2 in Device Configuration Registers table (Table 21-8)
- Removed erroneous statement regarding generation of CAN receive errors (see **Section 19.4.5 "Receive Errors"**)
- Electrical Specifications:
  - Resolved TBD values for parameters DO10, DO16, DO20, and DO26 (see Table 24-10)
  - 10-bit High-Speed ADC t_{PDU} timing parameter (time to stabilize) has been updated from 20 µs typical to 20 µs maximum (see Table 24-41)
  - Parameter OS65 (Internal RC Accuracy) has been expanded to reflect multiple Min and Max values for different temperatures (see Table 24-19)
  - Parameter DC12 (RAM Data Retention Voltage) Min and Max values have been updated (see Table 24-5)
  - Parameter D134 (Erase/Write Cycle Time) has been updated to include Min and Max values and the Typ value has been removed (see Table 24-12)
  - Removed parameters OS62 (Internal FRC Jitter) and OS64 (Internal FRC Drift) and Note 2 from AC Characteristics (see Table 24-18)
  - Parameter OS63 (Internal FRC Accuracy) has been expanded to reflect multiple Min and Max values for different temperatures (see Table 24-18)
  - Updated Min and Max values and Conditions for parameter SY11 and updated Min, Typ, and Max values and Conditions for parameter SY20 (see Table 24-21)
- Removed dsPIC30F6010 device reference from the third paragraph of **Section 7.0 "Data EEPROM Memory"**
- Removed IC5 and IC6 pin references from the 64-pin TQFP pin diagram (see **"Pin Diagram"**) and Figure 1-1
- Changed Interrupt Vectors 40-43 to Reserved (see Table 5-1)
- Updated PMD2 SFR – bits 15-12 and 7-4 are unimplemented (see Table 21-7)
- Additional minor corrections throughout the document